

## Amendments to the Claims

Please replace all prior versions and listings of claims with the following listing of claims.

### **LISTING OF CLAIMS:**

1. **(Previously Presented)** A lithographic projection apparatus, comprising:
  - a radiation system configured to supply a projection beam of radiation;
  - a patterning structure configured to pattern the projection beam according to a desired pattern;
  - a substrate table configured to hold a substrate;
  - a projection system configured to project the patterned beam onto a target portion of the substrate; and
  - a fluid processing cell in fluid communication with a surface of a substrate held on the substrate table, wherein the fluid processing cell is configured so that a fluid can be brought into contact with the substrate so as to interact with the target portion, the fluid processing cell comprises a plurality of separate chambers in fluid communication with respective areas of a substrate held on the substrate table, and the fluid processing cell is configured so that different areas of the substrate may be subjected to different fluid processes simultaneously or to a fluid process and a radiation exposure process simultaneously.
2. **(Original)** An apparatus according to claim 1, wherein the fluid processing cell comprises a plate member having walls projecting therefrom to contact the substrate to define the plurality of chambers.

3. **(Original)** An apparatus according to claim 2, wherein the plate member has within it a plurality of fluid channels communicating with the chambers.
4. **(Currently Amended)** An apparatus according to claim 1, wherein each chamber is ~~elongate~~ elongated and has a fluid inlet at a first end thereof and a fluid outlet at a second end thereof.
5. **(Previously Presented)** An apparatus according to claim 4, wherein the height of each chamber decreases from the fluid inlet toward the fluid outlet and capillary forces assist in removal of fluid from the cell.
6. **(Original)** An apparatus according to claim 1, wherein at least one surface of the fluid processing cell is provided with an anti-reflection coating.
7. **(Original)** An apparatus according to claim 1, wherein the height of each chamber is selected so as to minimize reflections of the radiation when a fluid is present in the chamber.
8. **(Original)** An apparatus according to claim 1, wherein the fluid processing cell is integrated into the substrate table.
9. **(Original)** An apparatus according to claim 1, wherein the fluid processing cell is separable from the substrate table and a substrate can be attached to the fluid processing cell before the cell and substrate are together loaded onto the substrate table.

10. (**Currently Amended**) An apparatus according to claim 1, wherein the fluid processing cell is separable from the substrate table and ~~a substrate can be placed on the substrate table and the fluid processing cell is~~ configured to be placed on the substrate, the substrate table, or both.

11. (**Previously Presented**) A device manufacturing method, comprising:  
providing a substrate to a substrate table in a lithographic projection system;  
providing a projection beam of radiation using a radiation system;  
patterning the projection beam in its cross-section;  
projecting the patterned beam of radiation onto a target portion of a layer of radiation-sensitive material; and  
processing an area of the substrate by exposing it to a fluid that interacts therewith to effect a process while the substrate is held by the substrate table, wherein the area of the substrate does not include the target portion and the projecting and processing are carried out at least partially simultaneously.

12. (**Previously Presented**) A method according to claim 11, wherein the interaction with the substrate comprises one or more steps selected from the group of:  
a chemical reaction with the substrate surface or compounds thereon;  
removal of part of the substrate or compounds thereon;  
addition of compounds to the substrate;  
washing; and  
modification of the surface or atomic or electronic structure of the substrate or compounds adhered thereto.

13. (**Previously Presented**) A method according to claim 11, further comprising a second processing of exposing a second area of the substrate to a second fluid that interacts therewith to effect a second process, the second area being different than the area, the second process being different than the process and the second processing being carried out at least partially simultaneously with the processing.

14. (**Currently Amended**) A lithographic apparatus, comprising:  
a patterning structure support that is constructed to support a patterning structure, the patterning structure capable of patterning a beam of radiation;

a substrate table for holding a substrate;

a projection system for projecting the patterned beam of radiation onto a target portion of the substrate; [[,]]

a fluid processing cell in fluid communication with a surface of a substrate held on the substrate table, the fluid processing cell comprising a plurality of separate chambers configured to not have fluid communication with one another and to simultaneously receive a fluid, wherein each chamber is configured to have [[in]] fluid communication with a different respective area[[s]] of the substrate held on the substrate table.

15. (**Currently Amended**) A lithographic apparatus according to claim 14, wherein at least two of the chambers receive different fluids for different exposure processes [[at]] on different respective areas of the substrate.

16. (**Currently Amended**) A device manufacturing method, comprising:  
providing a substrate;  
projecting a patterned beam of radiation onto a target portion of a layer of radiation-sensitive material on the substrate; and  
processing an area of said substrate by exposing it to a fluid that interacts therewith, the area of the substrate not including the target portion, wherein the projecting and the processing steps are carried out at least partially simultaneously.

17. (**Previously Presented**) The lithographic apparatus according to claim 14, wherein the fluid processing cell is configured to subject one area of the substrate to a fluid process and, simultaneously, subject another area of the substrate to a different fluid process, or to subject one area of the substrate to a fluid process and, simultaneously, subject another area of the substrate to a radiation exposure process.

18. (**New**) The lithographic apparatus according to claim 14, wherein each chamber includes a fluid inlet.

19. (**New**) The lithographic apparatus according to claim 14, wherein each chamber includes a fluid outlet.